

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

1tc2932hf#pbf

(Engineering Calculation)

TSSOP

(printed on: 2020-07-11 18:39:31)

**TOTAL MASS (g) : 0.070429**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.002169	1000000	30796.828125		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.024098	962000	342158.5625		
		Iron (Fe)	7439-89-6	0.000000	0	0		
		Phosphorus (P)	7723-14-0	0.000000	0	0		
		Zinc (Zn)	7440-66-6	0.000000	0	0		
		Nickel (Ni)	7440-02-0	0.000751	30000	10663.1708984		
		Silicon (Si)	7440-21-3	0.000163	1500	539.547851562		
		Magnesium (Mg)	7439-95-4	0.000038	1500	539.547851562		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.025050</b>	<b>1000000</b>	<b>355675.65625</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.001770	1000000	25136.2460938		
		<b>External Plating Total:</b>				<b>0.001770</b>	<b>1000000</b>	<b>25136.2460938</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000000	0	0		
		<b>Internal Plating Total:</b>				<b>0.000000</b>	<b>0</b>	<b>0</b>
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000743	750000	10549.5820312		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000248	250000	3521.26000977		
<b>Die Attach Total:</b>				<b>0.000991</b>	<b>1000000</b>	<b>14070.8417969</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.005414	135000	76871.3828125		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.034486	860000	489653.9375		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000201	5000	2853.92456055		
		<b>Encapsulation Total:</b>				<b>0.040101</b>	<b>1000000</b>	<b>569379.1875</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000348	1000000	4941.12304688		
					<b>TOTAL MASS (g) :</b>	<b>0.070429</b>		